

# PRODUCT DATA SHEET

# TACFlux® 26S

## Introduction

**TACFlux® 26S** is a NIA halogen-free, no-clean rework flux, which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

## Features

- Halogen-free – no intentionally added (NIA) halogens
- Suitable for Pb-free alloys
- Compatible with underfills
- Dipping with minimal bridging
- Designed for rework applications
- Low residue
- Bubble-free (airless) packaging

## Properties

Property	Value	Test Method
Flux Classification	RELO	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light Yellow	Visual
Typical Viscosity	13kcps	Brookfield HB DVII+-CP (20rpm)
SIR (Ohms)	Pass (>10 <sup>9</sup> after 7 days @ 85°C & 85% RH)	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Acid Value	39mg KOH/g	Titration
Shelf Life	6 months @ 0 to 30°C	Viscosity Change/ Microscope Examination
Typical Post Reflow Residual Weight	<10%	TGA

All information is for reference only. Not to be used as incoming product specifications.

## Application

**TACFlux® 26S** is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **TACFlux® 26S** can be used on many surface finishes including immersion Ag, Cu-OSP, AuNi, and AuPdNi, and is compatible with all standard flip-chip solders.

## Compatibility

The compatibility of flip-chip flux residues with epoxy-based capillary underfills is determined by measuring the shear strength of the interface between the post-reflow flux and the cured underfill. The best results for **TACFlux® 26S** have been observed with both amine- and acid anhydride-based capillary underfill chemistries.

## Cleaning

**TACFlux® 26S** is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

## Storage

**TACFlux® 26S** syringes and cartridges should be stored tip down at 0° to 30°C for maximum shelf life. **TACFlux® 26S** should be allowed to reach ambient temperature before use.

## Packaging

**TACFlux® 26S** is most commonly available in 10 and 30cc syringes. Other packaging can be provided to meet specific requirements.



From One Engineer To Another®



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### Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

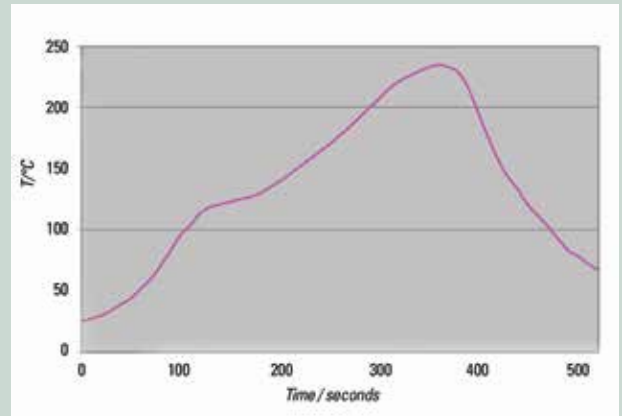
### Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

### Reflow

#### Recommended Profile:

Reflow Profile: SAC305



A short preheat (150°-160°C) for less than 45 seconds may be used to reduce voiding. The profile should ideally be a linear ramp at 2-3°C/second up to 20-30°C above solidus temperature, with a slow cool down afterwards of -0.5 to -0.2°C, and a minimum time above liquidus of 60 seconds.

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Contact our engineers today: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com](http://www.indium.com)



ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900



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